2SK1606

Silicon N-Channel Power F-MOS FET

■ Features

• High avalanche energy capacity

● V_{GSS}: 30V guaranteed

● Low R_{DS(on)}, high-speed switching characteristic

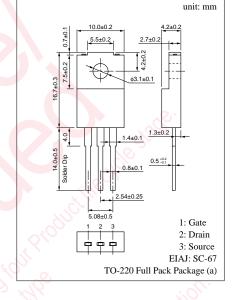
■ Applications

• High-speed switching (switching power supply)

• For high-frequency power amplification

■ Absolute Maximum Ratings $(T_C = 25^{\circ}C)$

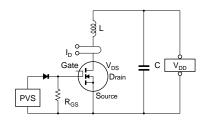
Parameter		Symbol	Ratings	Unit	
Drain to Source breakdown voltage		V _{DSS}	450	V	
Gate to Source voltage		V _{GSS}	±30	V	
Drain current	DC	I_D	±8	A	
	Pulse	I_{DP}	±16	A	
Avalanche energy capacity		EAS*	130	mJ	
Allowable power	$T_C = 25^{\circ}C$	D	50	W	
dissipation	$Ta = 25^{\circ}C$	P_{D}	2		
Channel temperature		T _{ch}	150	°C	
Storage temperature		T_{stg}	-55 to +150	°C	



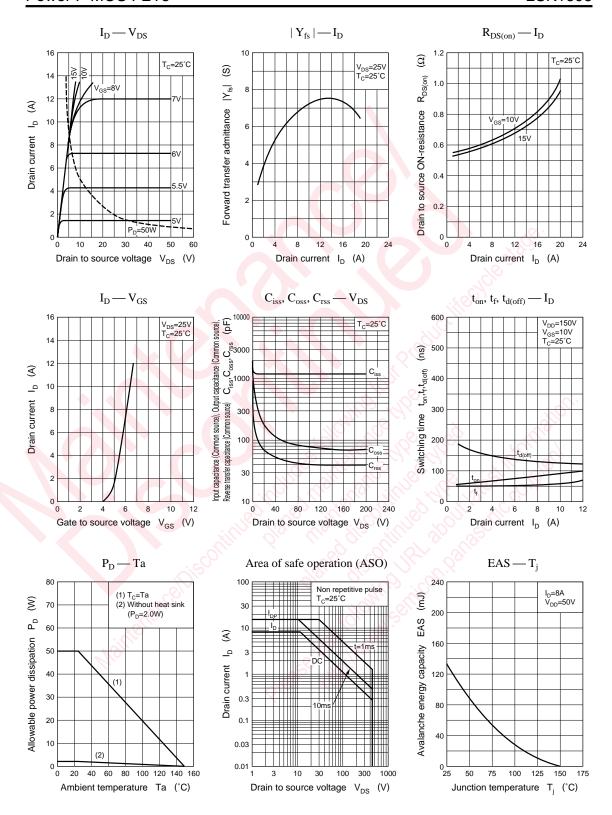
■ Electrical Characteristics (T_C = 25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Drain to Source cut-off current	I_{DSS}	$V_{DS} = 360V, V_{GS} = 0$	J. (2)		0.1	mA
Gate to Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0$	1, 7,4		±1	μΑ
Drain to Source breakdown voltage	$V_{\rm DSS}$	$I_D = 1 \text{mA}, V_{GS} = 0$	450	3)), (V
Avalanche energy capacity	EAS*	$L = 4.1 \text{mH}, I_D = 8 \text{A}, V_{DD} = 50 \text{V}$	130			mJ
Gate threshold voltage	V _{th}	$V_{DS} = 25V$, $I_D = 1mA$	1	3//	5	V
Drain to Source ON-resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 4A$		0.56	0.75	Ω
Forward transfer admittance	Y _{fs}	$V_{DS} = 25V, I_D = 4A$	3	5		S
Input capacitance (Common Source)	C _{iss}	$V_{DS} = 20V, V_{GS} = 0, f = 1MHz$	(S),	1300		pF
Output capacitance (Common Source)	C _{oss}			160		pF
Reverse transfer capacitance (Common Source)	C _{rss}	is Hay		70		pF
Turn-on time	t _{on}	V 10V 10S44 ***		70		ns
Fall time	$t_{\rm f}$	$V_{GS} = 10V, I_D = 4A$		50		ns
Turn-off time (delay time)	$t_{d(off)}$	$V_{DD} = 150V, R_L = 37.5\Omega$		150		ns

^{*} Avalanche energy capacity test circuit



^{*} Single pulse



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